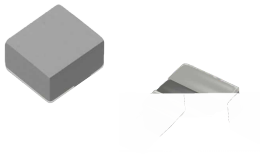
**MDTE Series**

Wire Wound Molded SMD Power Inductors

Size 25201B



**FEATURES**

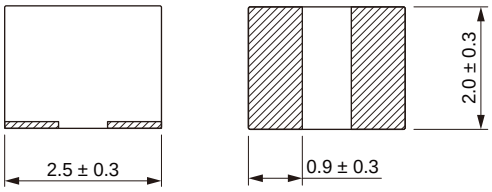
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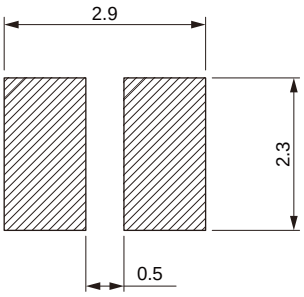
**APPLICATION**

- 
- 

Dimensions: [mm]




Land Pattern: [mm]




| | (μH) | | Saturation (A) | Saturation (A) | (A) | (A) | (mΩ) |
|---|---|---|---|---|---|---|---|
| | | | | | | | |
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Saturation Current will cause L to drop approximately 30%

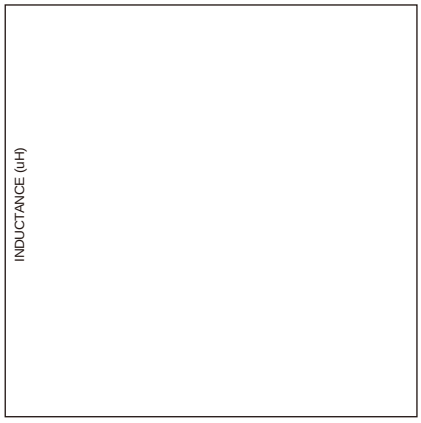
Temperature Rise Current: The actual value of DC current when the temperature rise is △T=40°C


**KOHER Electronic**

**4546 BATES DRIVE, YORBLINDA CA 92886 USA**

**714-325-4789 Contact@kohergroup.com**

## Typical Electrical Characteristics:



## Soldering Reflow:

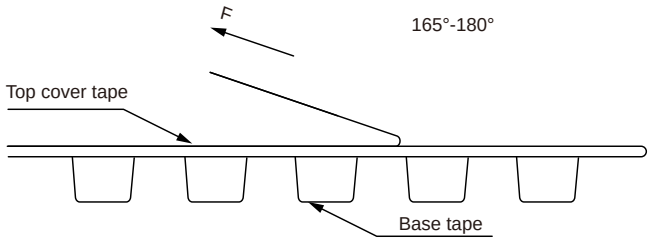
## Packaging Information:

### Tape Dimension:



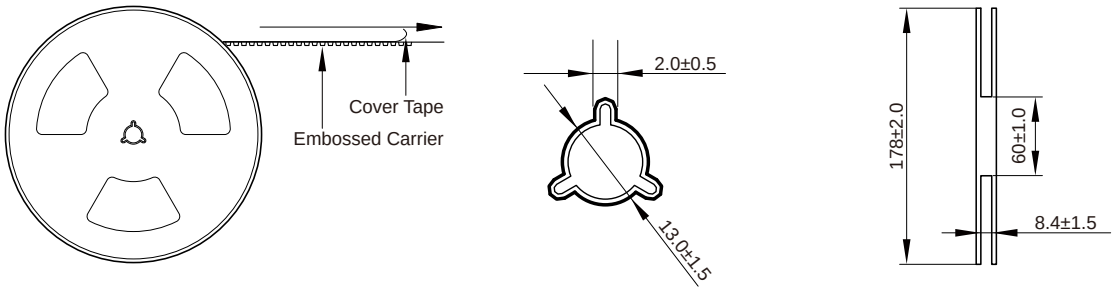
| Series | A0 (mm) | B0 (mm) | D (mm) | P0 (mm) | P1 (mm) | W (mm) | K0 (mm) | E (mm) | T (mm) |
|---|---|---|---|---|---|---|---|---|---|
| MDTE25201B | 2.4±0.1 | 2.9±0.1 | 1.5±0.1 | 4.0±0.1 | 4.0±0.1 | 8.0±0.1 | 1.4±0.1 | 1.75±0.1 | 0.25±0.05 |

### Peel force of top cover tape:

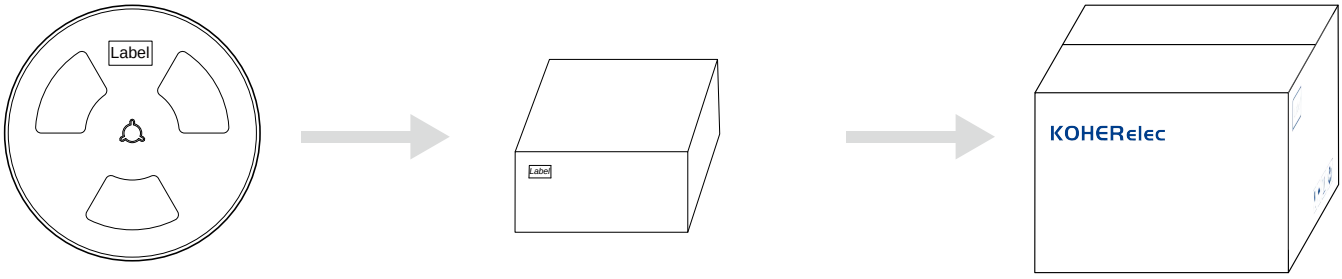



The peel force of top cover tape shall be between 0.1 to 0.98 N

## Reel Dimension：[mm]




## Packaging Quantity:




3000 Pcs/Reel

5 Reel /Inner box( 15K Pcs)

8 Inner box/Carton box(120K Pcs)

# Cautions and Warnings:

## Storage Conditions：

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max).If the storage period elapses, the soldering of the terminal electrodes may deteriorate.The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

## Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components.The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- Soldering corrections after mounting should be within the range of the conditions determined in the specifications.If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- Generally, Koher might not be familiar with either customer's specific application or actual requests as customer does.As a result customer shall be responsible for checking and confirming whether Koher product with the performance described in the product specification is suitable for using in customer's particular application or not.